PCN Number: 2022		220127000.1			PCN Date:		January 31, 2022		
				ab site (FFAB or GF al Assembly site/BO				ocess Technology, Die	
Customer	Contact:		PCN	<u>l Manager</u>		Dept:		Quality Services	
Proposed 1 st Ship Date:		1 // nr 3/1 ////		Estimat Availab			Date provided at sample request.		
Change Type:									
Assembly Site				Assembly Process			Asser	Assembly Materials	
Design				Electrical Specification			Mech	Mechanical Specification	
Test S	Site		Packing/Shipping/Labeling			Test	Test Process		
☐ Wafer Bump Site			Wafer Bump Material			Wafe	Wafer Bump Process		
		\boxtimes				Wafe	r Fab Process		
			Part number change						
PCN Details									

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab using a qualified process technology (FFAB or GFAB, SLM) and assembly (TIEMA) site/BOM options for selected devices as listed below in the product affected section.

	Current Fa	b Site	New Fab Site			
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter	
SFAB JI1		150 mm	FFAB	SLM	200 mm	
	JI1		GFAB	SLM	150 mm	
			GFAB	SLM	200 mm	

The die was also changed as a result of the process change.

Assembly Site material differences:

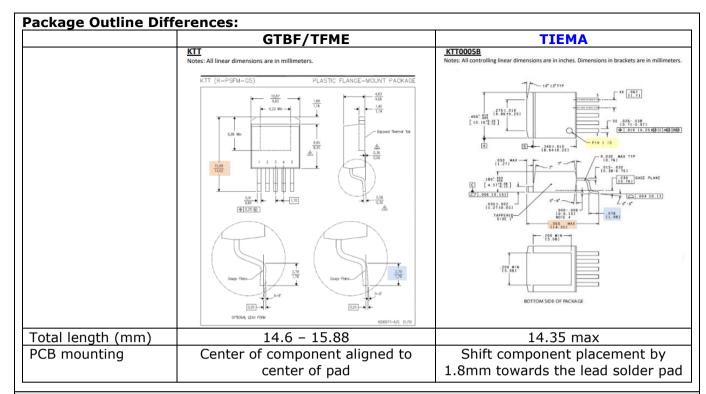
	TFME	GTBF	TIEMA
Mount compound	A-05	EY000006	8052550
Mold compound	R-07	EN0000030	8096890

Qual details are provided in the Qual Data Section.

Package Marking Differences:

Package Marking Differences.				
	GTBF/TFME	TIEMA		
Sample marking	O \T/ YMLLLS TL2575-12I \TI/ = TI LOGO YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = NOTCH POSITION	\T/ YMLLLS TL2575-12I O \TI/ = TI LOGO YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = NOTCH POSITION		
Notch position	Top middle	Bottom left		

PCN# 20220127000.1



Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the change in status of environmental ratings (Change From/Change To) following implementation of this change.

Change From:			
RoHS	REACH	Green Status	IEC 62474
RoHS = Yes	☐ REACH = Yes	☐ Green = Yes	☑ IEC 62474 = Yes

Change To:			
RoHS	REACH	Green Status	IEC 62474
\square RoHS = Exempt-7(a)	\boxtimes REACH = Affected	☐ Green = Yes	☐ IEC 62474 = Affected

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising
GFAB8	GF8	GBR	Greenock

Die Rev:

Current New

Current	ITCW
Die Rev [2P]	Die Rev [2P]
G	F

Assembly Site Information:

TIEMA	CU6	MYS	Melaka
GTBF	GTF	CHN	Shatin
TFME	NFM	CHN	Chongchuan
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City

Sample product shipping label (not actual product label)



(L)T0:1750



(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483812

(2P) REV: (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TL2575-05IKTTR	TL2575-33IKTTR	TL2575HV-05IKTTR	TL2575HV-15IKTTR
TL2575-12IKTTR	TL2575-ADJIKTTR	TL2575HV-12IKTTR	TL2575HV-ADJIKTTR

Change Qualification Report:

Approve Date 01/26/2021

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device <u>TL2575</u>	Qual Device: LM2577SX-ADJ
AC	Autoclave 121C	96 hours	3/231/0	
нвм	ESD - HBM	2000V	1/3/0	
HTOL	Life Test, 150C	300 hours	1/77/0	
HTSL	High Temp Storage Bake 150C	1000 hours	QBS	1/77/0
LU	Latch-up	125C	1/6/0	
ТНВ	Temperature Humidity Bias 85C/85%RH	1000 hours	3/231/0	
TC	Temperature Cycle, -65/150C	500 cycles	3/231/0	

- QBS: Qual By Similarity
- Qual family TL2575 is qualified at LEVEL3-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified RoHS-Exempt and Green

PCN# 20220127000.1

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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